



X-1574 US
10/796,471

PATENT
Conf. No.: 2282

IN THE UNITED STATES PATENT OFFICE

Applicant: Leilei Zhang
Assignee: Xilinx, Inc.
Title: Metal Lid with Improved Adhesion to Package Substrate
Serial No.: 10/796,471 Filing Date: March 9, 2004
Examiner: Jose R. Diaz Art Unit: 2815
Docket No.: X-1574 US Conf. No.: 2282

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT IN RESPONSE TO THE FINAL OFFICE ACTION

Dear Sir:

In response to the final Office action mailed from the Patent Office on October 16, 2006, please consider the following arguments and reconsider all pending claims. No amendments to the claims are made; therefore, this response does not include a listing of the claims.

Amendments to the Specification begin on page 2 of this paper.

Listing of the Claims there are no amendments to the claims but a listing of claims begins on page 4 of this paper.

Amendments to the Drawings begin on page 9 of this paper and include a replacement sheet.

Remarks begin on page 10 of this paper.

An **Appendix** including an amended drawing figures (Figures 2A-C) is attached following page 18.

Exhibit A, *Total Dispensing Solutions*, published by Asymtek (Spring 1998) is attached.

A **Statement of the Summary of the Interview** held on November 30, 2006 with Examiner Diaz is enclosed.

12/19/2006 BABRAHA1 00000003 240040 10796471

01 FC:1202 50.00 DA
02 FC:1201 200.00 DA